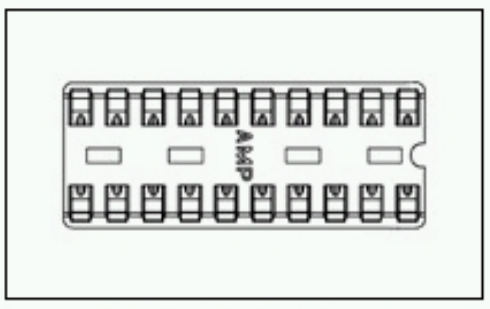
2-640464-4 Product Details

Live Product Chat



2-640464-4

TE Part Number: 2-640464-4
Active
Add to Part List

DIP Sockets

Not EU RoHS or ELV Compliant (Find RoHS Compliant Alternates)

Product Highlights:

- DIP Socket
- Number of Positions = 20
- Row-to-Row Spacing = 7.87 mm
- Thru Hole
- Mount Style = Vertical

View all Features | Find Similar Products

Quick Links

- Check Pricing & Availability
- Search for Tooling
- Product Feature Selector
- Contact Us About This Product
- Request Samples NEW!

Documentation & Additional Information

Product Drawings:
- SOCKET ASSY, DIP, 20 POS, DIPLOMATE DL (PDF, English)

Catalog Pages/Data Sheets:
- None Available

Product Specifications:
- None Available

Application Specifications:
- DIPLOMATE DL (Dual Leaf) DIP Sockets (PDF, English)

Instruction Sheets:
- None Available

CAD Files:
- None Available

List all Documents

Additional Information:
- Product Line Information

Related Products:
- Tooling

Product Features (Please use the Product Drawing for all design activity)

Product Type Features:
- Product Type = DIP Socket
- Number of Positions = 20
- Profile = Standard
- Frame Style = Closed
- Leg Style = Straight
- Proprietary Name = DIPLOMATE DL
- Color = Black
- Qty./Tube = 21
- Qty. Tubes/Box = 100
- Product Series = Standard
- Comment = ONLY sockets with straight solder tails are recommended for automatic insertion.

Electrical Characteristics:
- Insulation Resistance (MΩ) = 10,000
- Contact Resistance (mΩ) = 30

Termination Related Features:
- Termination (Solder) Post Length (mm [in]) = 3.25 [0.128]

Body Related Features:
- Row-to-Row Spacing (mm [in]) = 7.87 [0.310]
- Mount Style = Vertical
- Centerline (mm [in]) = 2.54 [0.100]

Contact Related Features:
- Contact Mount = Thru Hole
- Contact Material = Phosphor Bronze
- Contact Mating Area Plating Material = Gold (15)
- Contact Style = Stamped + Formed
- Mating Contact Type = Dual Leaf

Housing Related Features:
- Housing Material = Thermoplastic Glass Reinforced
- Housing Flammability Rating = UL 94V-0

Configuration Related Features:
- Height Above PC Board (mm [in]) = 5.33 [0.210]

Industry Standards:
- RoHS/ELV Compliance = Not ELV/RoHS compliant
- Lead Free Solder Processes = Wave solder capable to 240°C

Conditions for Usage:
- Temperature Range (°C) = 125

Operation/Application:
- Application = Production

Packaging Related Features:
- Packaging Method = Tube

Other:
- Brand = AMP

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